



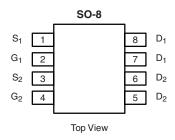
# N- and P-Channel 30-V (D-S) MOSFET

PRODUCT SUMMARY			
	V <sub>DS</sub> (V)	$R_{DS(on)}(\Omega)$	I <sub>D</sub> (A)
N-Channel	30	0.025 at V <sub>GS</sub> = 10 V	6.9
		0.035 at V <sub>GS</sub> = 4.5 V	5.8
P-Channel	- 30	0.032 at V <sub>GS</sub> = - 10 V	- 6.1
		0.045 at V <sub>GS</sub> = - 4.5 V	- 5.1

#### **FEATURES**

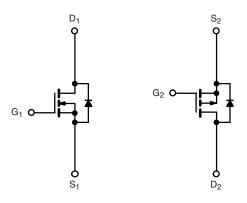
- Halogen-free According to IEC 61249-2-21 Definition
- TrenchFET® Power MOSFET
- 100 % R<sub>g</sub> Tested
- Compliant to RoHS Directive 2002/95/EC





Ordering Information: Si4542DY-T1-E3 (Lead (Pb)-free)

Si4542DY-T1-GE3 (Lead (Pb)-free and Halogen-free)



N-Channel MOSFET

P-Channel MOSFET

<b>ABSOLUTE MAXIMUM RATINGS</b> T <sub>A</sub> = 25 °C, unless otherwise noted						
Parameter		Symbol	N-Channel	P-Channel	Unit	
Drain-Source Voltage		$V_{DS}$	30	- 30	V	
Gate-Source Voltage		V <sub>GS</sub>	± 20	± 20		
Continuous Prais Current /T 150 °C\a	T <sub>A</sub> = 25 °C	- I <sub>D</sub>	6.9	- 6.1		
Continuous Drain Current (T <sub>J</sub> = 150 °C) <sup>a</sup>	T <sub>A</sub> = 70 °C		5.5	- 4.9	٨	
Pulsed Drain Current		I <sub>DM</sub>	40	- 40	Α	
Continuous Source Current (Diode Conduction) <sup>a</sup>		I <sub>S</sub>	1.7	- 1.7		
Marian na Daniar Dinain ation 8	T <sub>A</sub> = 25 °C	P <sub>D</sub> 2.0		.0	W	
Maximum Power Dissipation <sup>a</sup>	T <sub>A</sub> = 70 °C	' D	1.3		v v	
Operating Junction and Storage Temperature Range		T <sub>J</sub> , T <sub>stg</sub>	- 55 to 150		°C	

THERMAL RESISTANCE RATINGS					
Parameter	Symbol	N- or P-Channel	Unit		
Maximum Junction-to-Ambient <sup>a</sup>	R <sub>thJA</sub>	62.5	°C/W		

Notes:

a. Surface Mounted on FR4 board,  $t \leq 10 \ s.$ 

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Parameter	Symbol	Test Conditions		Min.	Typ.	Max.	Unit	
Static	1 - 7				<u> </u>			
Gate Threshold Voltage	V <sub>GS(th)</sub>	$V_{DS} = V_{GS}, I_{D} = 250 \mu\text{A}$	N-Ch	1.0				
		V <sub>DS</sub> = V <sub>GS</sub> , I <sub>D</sub> = - 250 μA	P-Ch	- 1.0			V	
Gate-Body Leakage	I <sub>GSS</sub>	$V_{DS} = 0 \text{ V}, V_{GS} = \pm 20 \text{ V}$	N-Ch			± 100	nA	
			P-Ch			± 100		
	I <sub>DSS</sub>	V <sub>DS</sub> = 30 V, V <sub>GS</sub> = 0 V	N-Ch			1		
Zero Gate Voltage Drain Current		V <sub>DS</sub> = - 30 V, V <sub>GS</sub> = 0 V	P-Ch			- 1	μΑ	
		$V_{DS} = 30 \text{ V}, V_{GS} = 0 \text{ V}, T_{J} = 55 ^{\circ}\text{C}$	N-Ch			25		
		$V_{DS} = -30 \text{ V}, V_{GS} = 0 \text{ V}, T_{J} = 55 ^{\circ}\text{C}$	P-Ch			- 25		
On-State Drain Current <sup>a</sup>	1-7	$V_{DS} \ge 5 \text{ V}, V_{GS} = 10 \text{ V}$	N-Ch	20			А	
	I <sub>D(on)</sub>	$V_{DS} \le -5 \text{ V}, V_{GS} = -10 \text{ V}$	P-Ch	- 20				
_		V <sub>GS</sub> = 10 V, I <sub>D</sub> = 6.9 A	N-Ch		0.020	0.025	<u> </u>	
		V <sub>GS</sub> = - 10 V, I <sub>D</sub> = - 6.1 A	P-Ch		0.026	0.032		
Drain-Source On-State Resistance <sup>a</sup>	R <sub>DS(on)</sub>	V <sub>GS</sub> = 4.5 V, I <sub>D</sub> = 5.8 A	N-Ch		0.026	0.035	Ω	
		V <sub>GS</sub> = - 4.5 V, I <sub>D</sub> = - 5.1 A	P-Ch		0.036	0.045		
Forward Transconductance <sup>a</sup>	9 <sub>fs</sub>	V <sub>DS</sub> = 15 V, I <sub>D</sub> = 6.9 A	N-Ch		25		S	
		V <sub>DS</sub> = - 15 V, I <sub>D</sub> = - 6.1 A	P-Ch		16			
Diode Forward Voltage <sup>a</sup>	V <sub>SD</sub>	I <sub>S</sub> = 1.7 A, V <sub>GS</sub> = 0 V	N-Ch			1.2		
		I <sub>S</sub> = - 1.7 A, V <sub>GS</sub> = 0 V	P-Ch			- 1.2	V	
Dynamic <sup>b</sup>	1	,	"					
Total Cata Charge		N-Channel	N-Ch		30	50	nC	
Total Gate Charge	$Q_g$		P-Ch		32	50		
Gate-Source Charge	Q <sub>gs</sub>	$V_{DS} = 15 \text{ V}, V_{GS} = 10 \text{ V}, I_{D} = 6.9 \text{ A}$	N-Ch		7.5			
- Catto Couros Charge	∽gs	P-Channel	P-Ch		7.0			
Gate-Drain Charge	Q <sub>gd</sub>	$V_{DS} = -15 \text{ V}, V_{GS} = -10 \text{ V}, I_{D} = -6.1 \text{ A}$	N-Ch		3.5			
			P-Ch		5.0			
Gate Resistance	R <sub>g</sub>		N-Ch	0.5	2	3.4	Ω	
			P-Ch N-Ch	2	4	6.8	1	
Turn-On Delay Time	t <sub>d(on)</sub>	N-Channel $V_{DD}$ = 15 V, $R_L$ = 10 $\Omega$	P-Ch		12 10	20 20		
			N-Ch		10	20	ns	
Rise Time		$I_D \cong 1 \text{ A, } V_{GEN} = 10 \text{ V, } R_g = 6 \Omega$	P-Ch		10	20		
Turn-Off Delay Time	t <sub>d(off)</sub>	- P-Channel	N-Ch		60	90		
		$V_{DD} = -15 \text{ V}, R_L = 10 \Omega$	P-Ch		55	80		
Fall Time	t <sub>f</sub>	$I_D \cong -1$ A, $V_{GEN} = -10$ V, $R_g = 6 \Omega$	N-Ch		15	30		
		C	P-Ch		25	40		
Source-Drain	t <sub>rr</sub>	I <sub>F</sub> = 1.7 A, dI/dt = 100 A/μs	N-Ch		50	90		
Reverse Recovery Time		I <sub>F</sub> = - 1.7 A, dI/dt = 100 A/μs	P-Ch		50	90		
Reverse Recovery Time	Q <sub>rr</sub>	I <sub>F</sub> = 1.7 A, dI/dt = 100 A/μs	N-Ch		45	-	nC	
neverse necovery Time	<b>∀</b> rr	I <sub>F</sub> = - 1.7 A, dl/dt = 100 A/μs	P-Ch		55		IIC	

#### Notes:

- a. Pulse test; pulse width  $\leq 300~\mu s,$  duty cycle  $\leq 2~\%.$
- b. Guaranteed by design, not subject to production testing.

Stresses beyond those listed under "Absolute Maximum Ratings" may cause permanent damage to the device. These are stress ratings only, and functional operation of the device at these or any other conditions beyond those indicated in the operational sections of the specifications is not implied. Exposure to absolute maximum rating conditions for extended periods may affect device reliability.



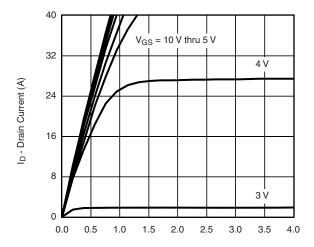


0.05

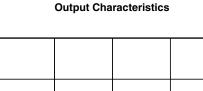
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#### N-CHANNEL TYPICAL CHARACTERISTICS 25 °C unless otherwise noted



V<sub>DS</sub> - Drain-to-Source Voltage (V)



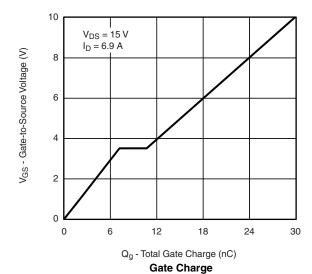
 $\mathsf{R}_{\mathsf{DS}(\mathsf{on})}$  - On-Resistance  $(\Omega)$  $V_{GS} = 4.5 V$ 0.03 0.02 V<sub>GS</sub> = 10 V 0.01 0.00

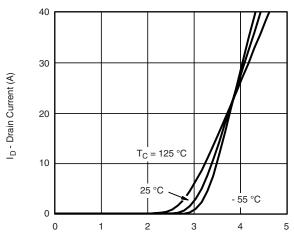
10

I<sub>D</sub> - Drain Current (A) On-Resistance vs. Drain Current

20

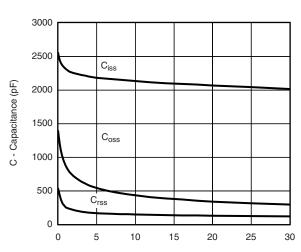
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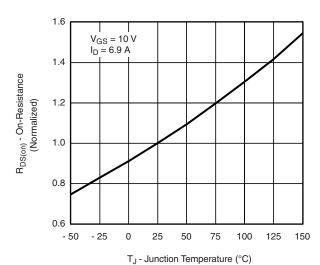
V<sub>GS</sub> - Gate-to-Source Voltage (V)

#### **Transfer Characteristics**



V<sub>DS</sub> - Drain-to-Source Voltage (V)

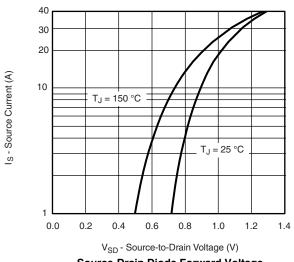
#### Capacitance

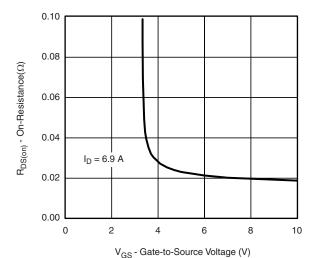


On-Resistance vs. Junction Temperature

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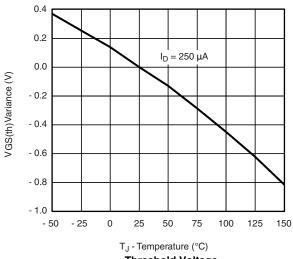
#### N-CHANNEL TYPICAL CHARACTERISTICS 25 °C unless otherwise noted

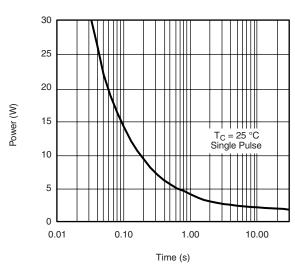




Source-Drain Diode Forward Voltage

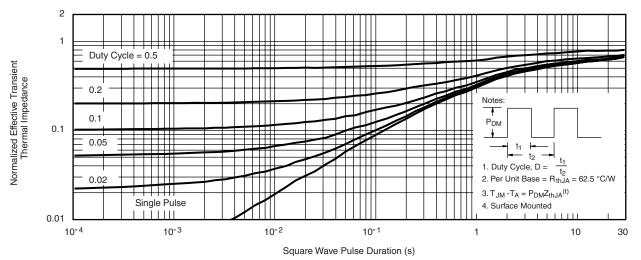






**Threshold Voltage** 

Single Pulse Power

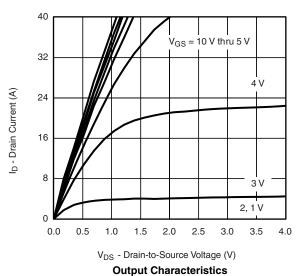


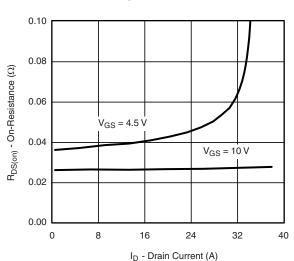
Normalized Thermal Transient Impedance, Junction-to-Ambient



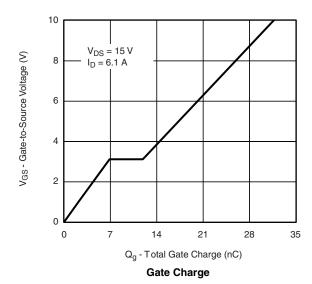


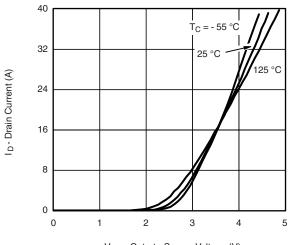
#### P-CHANNEL TYPICAL CHARACTERISTICS 25 °C unless otherwise noted



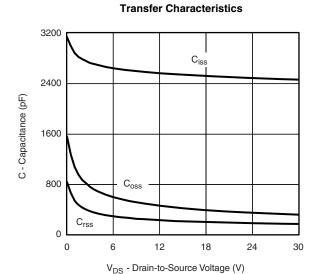


On-Resistance vs. Drain Current

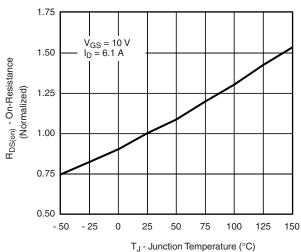




V<sub>GS</sub> - Gate-to-Source Voltage (V)



Capacitance

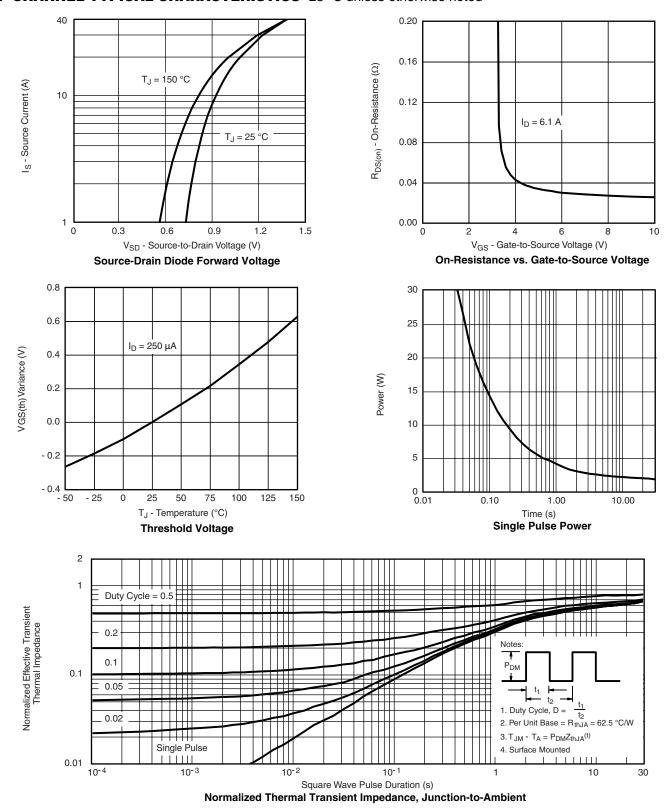


On-Resistance vs. Junction Temperature

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#### P-CHANNEL TYPICAL CHARACTERISTICS 25 °C unless otherwise noted



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